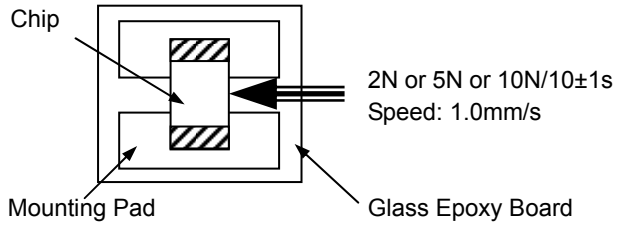
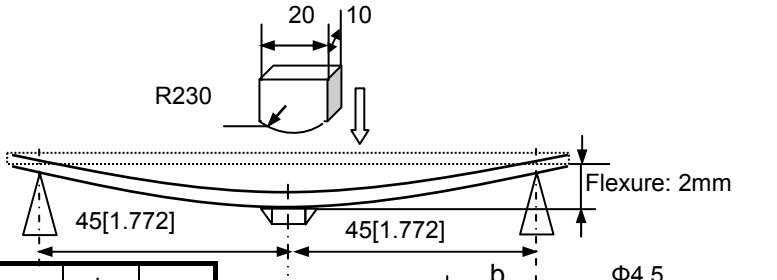
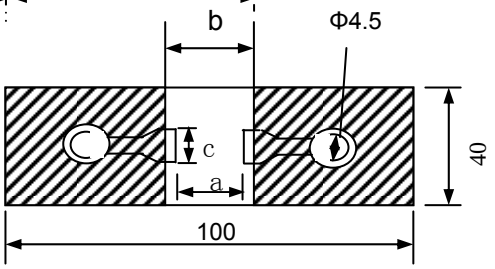
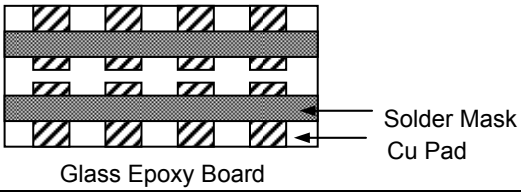
RELIABILITY AND TEST CONDITIONS

Multilayer Chip Ferrite Bead (GZ/GZ-C/SZ/SZ-C/PZ/UPZ/EPZ/HZ/HPZ Series)

<table>
<tr><th>Items</th><th>Requirements</th><th>Test Methods and Remarks</th></tr>
<tr><td>1. Operating Temperature Range</td><td colspan="2">-55℃ to +125℃</td></tr>
<tr><td>2. Storage Temperature Range</td><td colspan="2">-55℃ to +125℃</td></tr>
<tr><td>3. Terminal Strength</td><td>No removal or split of the termination or other defects shall occur.</td><td>① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder. Then apply a force in the direction of the arrow.
② 2N force for 0603 series.
③ 5N force for 1005 and 1608 series.
④ 10N force for 2010, 2012, 3216,4516 and 4030 series.
⑤ Keep time: 10±1s
 
</td></tr>
<tr><td rowspan="2">4. Resistance to Flexure</td><td>No visible mechanical damage.</td><td>① Solder the chip to the test jig (glass epoxy board) using a eutectic solder. Then apply a force in the direction shown as the following figure.
② Flexure: 2mm
③ Pressurizing Speed: 0.5mm/sec
④ Keep time: ≥30 sec</td></tr>
<tr><td colspan="2"> 

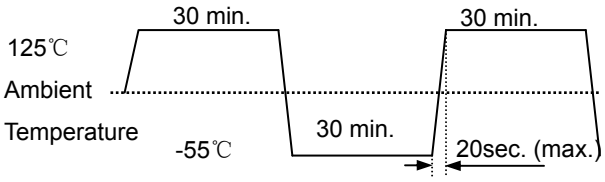
Unit: mm [inch]


<table>
<tr><th>Type</th><th>a</th><th>b</th><th>c</th></tr>
<tr><td>0603[0201]</td><td>0.25</td><td>0.8</td><td>0.3</td></tr>
<tr><td>1005[0402]</td><td>0.4</td><td>1.5</td><td>0.5</td></tr>
<tr><td>1608[0603]</td><td>1.0</td><td>3.0</td><td>1.2</td></tr>
<tr><td>2012[0805]</td><td>1.2</td><td>4.0</td><td>1.65</td></tr>
<tr><td>3216[1206]</td><td>2.2</td><td>5.0</td><td>2.0</td></tr>
<tr><td>4030[1612]</td><td>1.9</td><td>6.1</td><td>3.2</td></tr>
<tr><td>4516[1806]</td><td>2.8</td><td>8.5</td><td>2.0</td></tr>
</table></td></tr>
<tr><td>5. Vibration</td><td>① No visible mechanical damage.
② Impedance change: Within ±20%.</td><td>① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder.
② The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5 mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz.
③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (total of 6 hours).
 
</td></tr>
</table>

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110 **Tel**: 0086-755-29832660 **Fax**: 0086-755-82269029 **E-Mail**: sunlord@sunlordinc.com

RELIABILITY AND TEST CONDITIONS

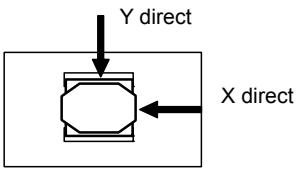
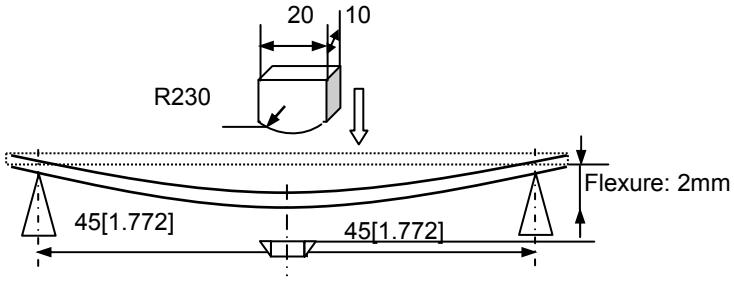
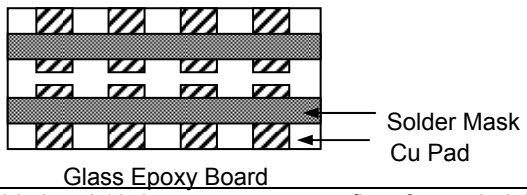
Multilayer Chip Ferrite Bead (GZ/GZ-C/SZ/SZ-C/PZ/UPZ/EPZ/HZ/HPZ Series)

Items	Requirements	Test Methods and Remarks
6. Dropping	① No visible mechanical damage. ② Impedance change: Within ±20%.	① Drop chip bead 10 times on a concrete floor from a height of 100 cm.
7. Temperature	① Impedance change should be within ±20% of initial value measuring at 20℃.	① Temperature range:-55℃ to +125℃ Reference temperature: +20℃
8. Solderability	① No visible mechanical damage. ② Wetting shall be exceeded 75% coverage for 0603 series, and 95% coverage for the other.	① Solder temperature: 240±2℃ ② Duration: 3 sec ③ Solder: Sn/3.0Ag/0.5Cu ④ Flux: 25% Resin and 75% ethanol in weight
9. Resistance to Soldering Heat	① No visible mechanical damage. ② Wetting shall be exceeded 75% coverage for 0603 series, and 95% coverage for the other ③ Impedance change: Within ±20%.	① Solder temperature: 260±3℃ ② Duration: 5 sec ③ Solder: Sn/3.0Ag/0.5Cu ④ Flux: 25% Resin and 75% ethanol in weight ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
10. Thermal Shock	① No visible mechanical damage. ② Impedance change: Within ±20%.	① Temperature and time: -55℃ for 30±3 min →125℃ for 30±3min ② Transforming interval: Max. 20 sec ③ Tested cycle: 100 cycles ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring. 
11. Resistance to Low Temperature	① No visible mechanical damage. ② Impedance change: Within ±20%.	① Temperature: -55±2℃ ② Duration: 1000^{+24} hours ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
12. Damp Heat (Steady States)	① No visible mechanical damage. ② Impedance change: Within ±20%.	① Temperature: 60±2℃ ② Humidity: 90% to 95% RH ③ Duration: 1000^{+24} hours ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
13. Loading Under Damp Heat	① No visible mechanical damage. ② Impedance change: Within ±20%.	① Temperature: 60±2℃ ② Humidity: 90% to 95% RH ③ Duration: 1000^{+24} hours ④ Applied current: Rated current ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
14. Loading at High Temperature (Life Test)	① No visible mechanical damage. ② Impedance change: Within ±20%.	① Temperature: GZ&GZ-C&SZ&SZ-C&HZ series: 125±2℃ PZ&UPZ&EPZ&HPZ series: 85±2℃ ② Duration: 1000^{+24} hours ③ Applied current: Rated current. ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110 **Tel**: 0086-755-29832660 **Fax**: 0086-755-82269029 **E-Mail**: sunlord@sunlordinc.com

RELIABILITY AND TEST CONDITIONS

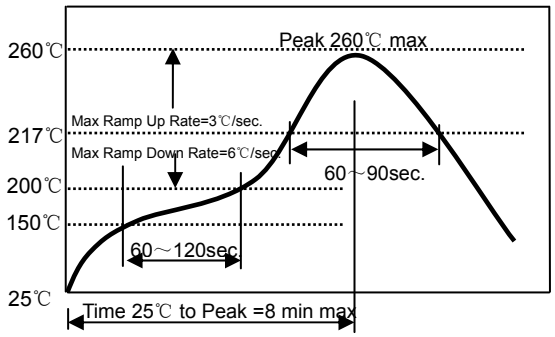
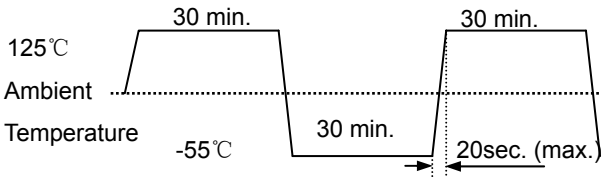
Wire Wound Chip Ferrite Bead (SPH3015HZSeries)

Items	Requirements	Test Methods and Remarks
1. Operating Temperature Range	-40℃ ~ +125℃	
2. Storage Temperature Range	-40℃ ~ +125℃	
3. Terminal Strength	No removal or split of the termination or other defects shall occur.	① Solder the inductor to the testing jig (glass epoxy board shown in using eutectic solder. Then apply a force in the direction of the arrow. ② 10N force. ③ Keep time: 5s 
4. Resistance to Flexure	No visible mechanical damage.	① Solder the chip to the test jig (glass epoxy board) using eutectic solder. Then apply a force in the direction shown the following figure. ② Flexure: 2mm ③ Pressurizing Speed: 0.5mm/sec ④ Keep time: 30±1s ⑤ Test board size: 100X40X1.0 ⑥ Land dimension: 3015
		
5. Vibration	① No visible mechanical damage. ② Impedance change: Within ±10%	① Solder the chip to the testing jig (glass epoxy board shown as(the following figure) using eutectic solder. ② The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz. ③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (total of 6 hours). 
6. Dropping	① No visible mechanical damage. ② Impedance change: Within ±20%.	Drop chip bead 10 times on a concrete floor from a height of 100 cm.

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110 **Tel**: 0086-755-29832660 **Fax**: 0086-755-82269029 **E-Mail**: sunlord@sunlordinc.com

RELIABILITY AND TEST CONDITIONS

Wire Wound Chip Ferrite Bead (SPH3015HZSeries)

Items	Requirements	Test Methods and Remarks
7. Temperature	Impedance change: Within ±20%	① Temperature: -40℃~+125℃ ② With a reference value of +20℃, change rate shall be calculated
8. Solderability	90% or more of electrode area shall be coated by new solder.	① The test samples shall be dipped in flux, and then immersed in molten solder. ② Solder temperature: 245±5℃ ③ Duration: 5±1 sec. ④ Solder: Sn/3.0Ag/0.5Cu ⑤ Flux: 25% resin and 75% ethanol in weight ⑥ Immersion depth: all sides of mounting terminal shall be immersed
9. Resistance to Soldering Heat	① No visible mechanical damage. ② Impedance change: Within ±10%	① Re-flowing Profile: Please refer to the following figure ② Test board thickness: 1.0mm ③ Test board material: glass epoxy resin ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring 
10. Thermal Shock	① No visible mechanical damage. ② Impedance change: Within ±10%	① Temperature and time: -40±3℃ for 30±3 min→125℃ for 30±3min ② Transforming interval: Max. 20 sec ③ Tested cycle: 100 cycles ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring. 
11. Resistance to Low Temperature	① No visible mechanical damage ② Impedance change: Within ±10%	① Temperature: -40±3℃ ② Duration: $1000^{\pm 24}$ hours ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring
12. Damp Heat (Steady States)	① No mechanical damage. ② Impedance change: Within ±10%	① Temperature: 60±2℃ ② Humidity: 90% to 95%RH ③ Duration: $1000^{\pm 24}$ hours ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring
13.istance to High Temperature	③ No visible mechanical damage Impedance change: Within ±10%	① Temperature:125±2℃ ② Duration: $1000^{\pm 24}$ hours ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110 **Tel**: 0086-755-29832660 **Fax**: 0086-755-82269029 **E-Mail**: sunlord@sunlordinc.com

RELIABILITY AND TEST CONDITIONS

Wire Wound Chip Ferrite Bead (SPH3015HZSeries)

Item	Requirements	Test Methods and Remarks
14. Loading Under Damp Heat	① No mechanical damage. ② Impedance change: Within ±10%	① Temperature: 60±2℃ ② Humidity: 90% to 95% RH ③ Applied current: Rated current ④ Duration:$1000^{\pm 24}$ hours ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring
15.Loading at High Temperature (Life Test)	① No mechanical damage. ② Impedance change: Within ±10%	① Temperature: 85±2℃ ② Applied current: Rated current ③ Duration: $1000^{\pm 24}$ hours ① The chip shall be stabilized at normal condition for 1~2 hours before measuring

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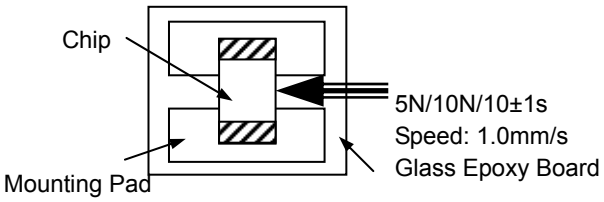
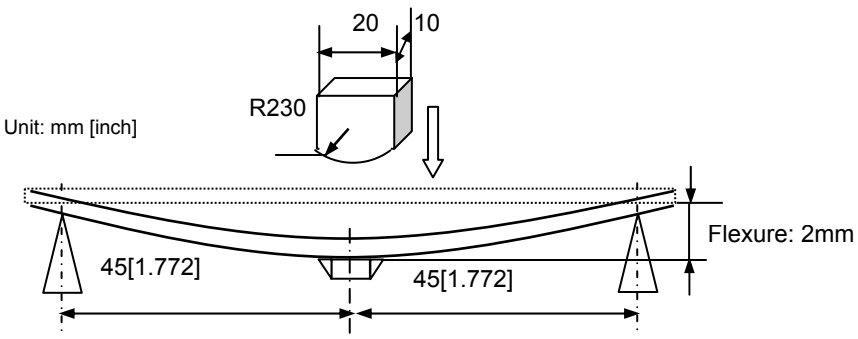
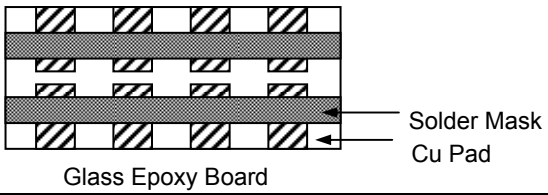
RELIABILITY AND TEST CONDITIONS

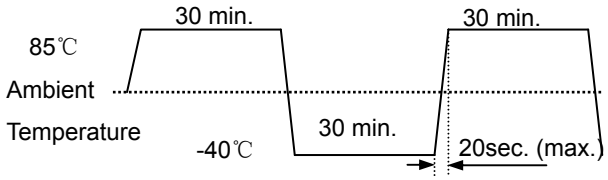
Chip 3-Terminal EMI Filters (MFL Series)

<table>
<tr><th>Items</th><th>Requirements</th><th>Test Methods and Remarks</th></tr>
<tr><td>1. Operating Temperature Range</td><td colspan="2">-40℃ to +85℃</td></tr>
<tr><td>2. Storage Temperature Range</td><td colspan="2">-40℃ to +85℃</td></tr>
<tr><td>3. Terminal Strength</td><td>No removal or split of the termination or other defects shall occur.</td><td>① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder. Then apply a force in the direction of the arrow.
② 5N force for 1608 series
③ 10N force for 2012 series
④ Keep time: 10±1s
 
</td></tr>
<tr><td rowspan="2">4. Resistance to Flexure</td><td>No visible mechanical damage.</td><td>① Solder the chip to the test jig (glass epoxy board) using a eutectic solder. Then apply a force in the direction shown as the following figure. Solder the chip to the test jig (glass epoxy board) using eutectic solder. Then apply a force in the direction.
② Flexure: 2mm
③ Pressurizing Speed: 0.5mm/sec
④ Keep time: ≥30 sec</td></tr>
<tr><td colspan="2"> 
</td></tr>
<tr><td>5. Vibration</td><td>No visible mechanical damage.</td><td>① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder.
② The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz.
③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (total of 6 hours).
 
</td></tr>
<tr><td>6. Dropping</td><td>No visible mechanical damage.</td><td>Drop the chip 10 times on a concrete floor from a height of 100 cm.</td></tr>
<tr><td>7. Solderability</td><td>① No visible mechanical damage.
② Wetting shall be exceeded 75% coverage.</td><td>① Solder temperature: 240±2℃
② Duration: 3 sec
③ Solder: Sn/3.0Ag/0.5Cu
④ Flux: 25% Resin and 75% ethanol in weight</td></tr>
</table>

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110 **Tel**: 0086-755-29832660 **Fax**: 0086-755-82269029 **E-Mail**: sunlord@sunlordinc.com

RELIABILITY AND TEST CONDITIONS

Chip 3-Terminal EMI Filters (MFL Series)

Items	Requirements	Test Methods and Remarks
8. Resistance to Soldering Heat	No visible mechanical damage.	① Solder temperature: 260±3℃ ② Duration: 5 sec. ③ Solder: Sn/3.0Ag/0.5Cu ④ Flux: 25% Resin and 75% ethanol in weight. ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
9. Thermal Shock	① No visible mechanical damage. ② Insulation resistance: Satisfy electrical characteristics	① Temperature and time: -40℃ for 30±3 min→85℃ for 30±3min ② Transforming interval: Max. 20 sec ③ Tested cycle: 100 cycles ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring. 
10. Damp Heat (Steady States)	① No visible mechanical damage ② Insulation resistance: Satisfy electrical characteristics	① Temperature: 60±2℃ ② Humidity: 90% to 95% RH ③ Duration: 1000^{+24} hours ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
11. Loading Under Damp Heat	① No visible mechanical damage ② Insulation resistance: Satisfy electrical characteristics	① Temperature: 40±2℃ ② Humidity: 90% to 95% RH ③ Duration: 1000^{+24} hours ④ Applied current: Rated current ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
12. Loading at High Temperature (Life Test)	① No visible mechanical damage ② Insulation resistance: Satisfy electrical characteristics	① Temperature: 85±2℃ ② Duration: 1000^{+24} hours ③ Applied current: Rated current ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

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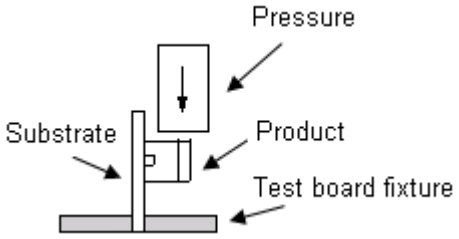
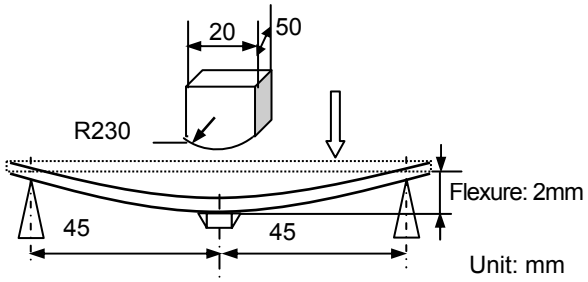
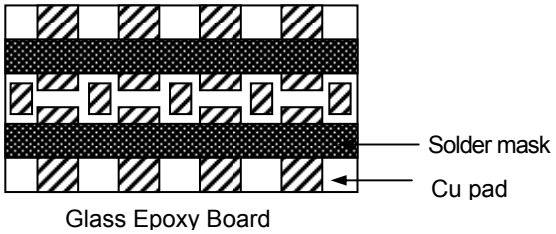
RELIABILITY AND TEST CONDITIONS

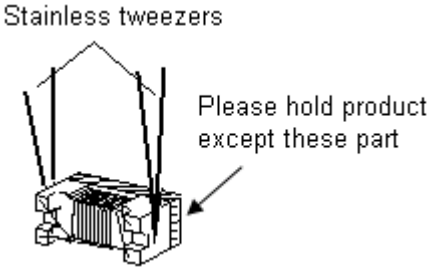
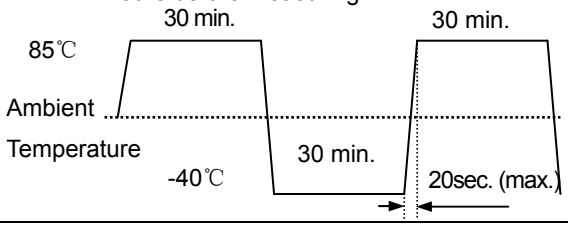
Wire Wound Chip Common Mode Choke Coil (SDCW/SDCW-H/-CH/-U/-S/-C Series)

Item	Requirements	Test Methods and Remarks
1. Operating Temperature Range	-40℃ to +85℃	
2. Storage Temperature Range	-40℃ to +85℃	
3. Terminal strength	No removal or split of the termination or other defects shall occur.	① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder. Then apply a force in the direction of the arrow. ② 3N force for 1210 and 1608 series ③ 5N force for 2012 series ④ 8N force for 3216 series. ⑤ Keep time: 30±1s 
4. Resistance to Flexure	No visible mechanical damage.	① Solder the chip to the test jig (glass epoxy board) using eutectic solder. Then apply a force in the direction shown as the following figure. ② Flexure: 2mm ③ Pressurizing Speed: 0.5mm/sec ④ Keep time: 5s 
5. Vibration	No visible mechanical damage.	① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder. ② The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz. ③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions (total of 6 hours). 

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110 **Tel**: 0086-755-29832660 **Fax**: 0086-755-82269029 **E-Mail**: sunlord@sunlordinc.com

RELIABILITY AND TEST CONDITIONS

Wire Wound Chip Common Mode Choke Coil (SDCW/SDCW-H/-CH/-U/-S/-C Series)

Item	Requirements	Test Methods and Remarks
6. Dropping	No visible mechanical damage.	Drop the chip 3 times on a concrete floor from a height of 100 cm.
7. Solderability	Wetting shall be exceeded 90% coverage, except welding points.	① Solder temperature: 240±2℃ ② Duration: 4±1sec ③ Solder: Sn/3.0Ag/0.5Cu ④ Flux: 25% Resin and 75% ethanol in weight 
8. Resistance to soldering heat	① No visible mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Reflow soldering. ② The chip shall be stabilized at normal condition for 1~2 hours before measuring. ③ Please reference the Re-flowing Profile in Soldering and Notice for EMC Components
9. Temperature Characteristics	① No visible mechanical damage. ② Impedance change: Within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature range: -40℃ to +85℃ ② Reference temperature: +20℃
10. Thermal shock	① No mechanical damage. ② Impedance change: Within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature and time: -40℃ for 30±3 min →85℃ for 30±3min ② Transforming interval: Max. 20 sec ③ Tested cycle: 250 cycles ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring. 
11. Resistance to low temperature	① No mechanical damage. ② Impedance change: Within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature: -40±2℃ ② Duration: 500^{+12} hours ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

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RELIABILITY AND TEST CONDITIONS

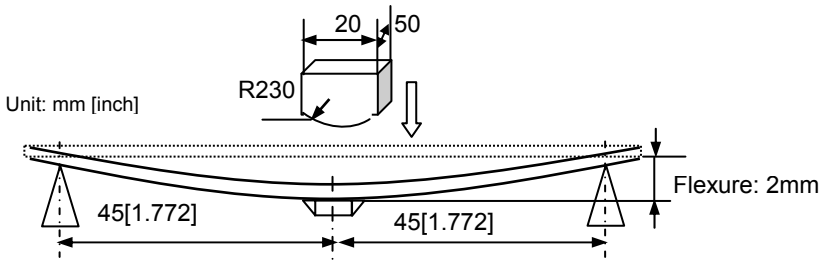
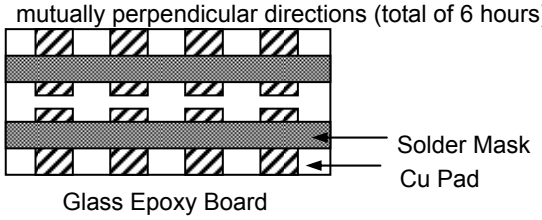
Wire Wound Chip Common Mode Choke Coil (SDCW/SDCW-H/-CH /-U/-S/-C Series)

Item	Requirements	Test Methods and Remarks
12. Damp heat (Steady states)	① No visible mechanical damage. ② Impedance change: Within ±20%. ③ Insulation Resistance: 10MΩ Min.	② Temperature: 60±2℃ ③ Humidity: 90% to 95% RH ④ Duration: 500^{+12} hours ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
13. Loading under damp heat	① No visible mechanical damage. ② Impedance change: Within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature: 60±2℃ ② Humidity: 90% to 95% RH ③ Duration: 500^{+12} hours ④ Applied current: Rated current. ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
14. Loading at high temperature (Life test)	① No visible mechanical damage. ② Impedance change: Within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature: 85±2℃ ② Duration: 500^{+12} hours ③ Applied current: Rated current ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110 **Tel**: 0086-755-29832660 **Fax**: 0086-755-82269029 **E-Mail**: sunlord@sunlordinc.com

RELIABILITY AND TEST CONDITIONS

Multilayer Chip Common Mode Choke Coil (SDMM0806 Series)

Items	Requirements	Test Methods and Remarks
1. Operating Temperature Range	-40℃ to +85℃	
2. Storage Temperature Range	-40℃ to +85℃	
3. Resistance to Flexure	No visible mechanical damage.	① Solder the chip to the 1.0mm test jig (glass epoxy board) using a eutectic solder. Then apply a force in the direction shown as the following figure. ② Flexure: 2mm ③ Pressurizing Speed: 0.5mm/sec ④ Keep time: 5 sec
		
4. Vibration	① No visible mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Solder the chip to the testing jig (glass epoxy board shown as the following figure) using eutectic solder. ② The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz. ③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (total of 6 hours). 
5. Dropping	① No visible mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	Drop the chip 3 times on a concrete floor from a height of 100 cm.
6. Solderability	① No visible mechanical damage. ② Wetting shall be exceeded 90% coverage.	① Solder temperature: 240±2℃ ② Duration: 3sec ③ Solder: Sn/3.0Ag/0.5Cu ④ Flux: 25% Resin and 75% ethanol in weight
7. Resistance to Soldering Heat	① No visible mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Solder temperature: 260±3℃ ② Duration: 5 sec. ③ Solder: Sn/3.0Ag/0.5Cu ④ Flux: 25% Resin and 75% ethanol in weight. ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

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RELIABILITY AND TEST CONDITIONS

Multilayer Chip Common Mode Filter (SDMM0806 Series)

Items	Requirements	Test Methods and Remarks
8.Temperature Characteristics	① No visible mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature range: -40℃~+85℃. ② Reference temperature: +20℃.
9. Thermal Shock	① No visible mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature and time: -40℃ for 30±3 min→85℃ for 30±3min ② Transforming interval: Max. 20 sec ③ Tested cycle: 100 cycles ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
10.Resistance to low temperature	① No mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature: -40±2℃ ② Duration: 1000^{+12} hours. ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
11. Damp Heat (Steady States)	① No mechanical damage. ② Impedance change: within ±20%. Insulation Resistance: 10MΩ Min.	① Temperature: 60±2℃ ② Humidity: 90% to 95% RH ③ Duration: 1000^{+24} hours ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
12.Loading under damp heat	① No visible mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature: 60±2℃. ② Humidity: 90% to 95% RH. ③ Duration: 1000^{+12} hours. ④ Applied current: Rated current. ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
13.Loading at high temperature (Life test)	① No visible mechanical damage. ② Impedance change: within ±20%. ③ Insulation Resistance: 10MΩ Min.	① Temperature: 85±2℃. ② Duration: 1000^{+12} hours. ③ Applied current: Rated current. ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

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